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JUN 30 2006

**CHIP-PACKAGING WITH BONDING OPTIONS HAVING A PLURALITY OF
PACKAGE SUBSTRATES**

Appl. No.	:	10/709,427	Confirmation No. 3426
Applicant	:	Cheng-Yen Huang	
Filed	:	May 5, 2004	
TC/A.U.	:	2822	
Examiner	:	Prenty, Mark V	
Docket No.	:	FTCP0036USA0	
Customer No.	:	27765	

Commissioner for Patents
P.O. Box 1450
Alexandria VA 22313-1450

AMENDMENT AND REQUEST FOR CONTINUED EXAMINATION

5 Sir:

In response to the Office action of March 31, 2006, please amend the above-identified application as follows:

Amendments to the Specification begin on page 2 of this paper.

10 **Amendments to the Claims** are reflected in the listing of claims which begins on page 8 of this paper.

Amendments to the Drawings begin on page 10 of this paper and include two new sheets.

Remarks/Arguments begin on page 11 of this paper.

An **Appendix** including amended drawing figures is attached following page 15 of this paper.

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